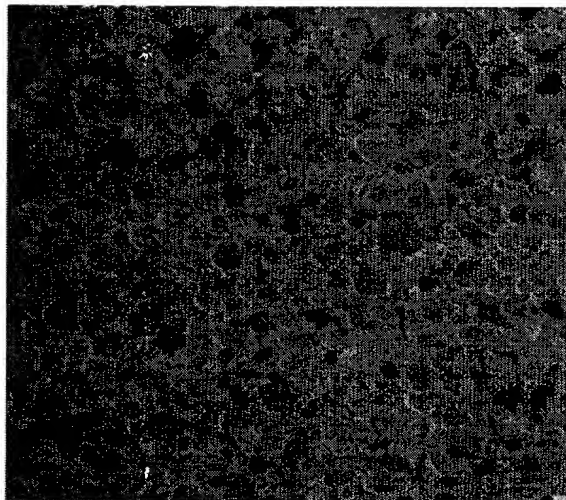


Prior Art

FIG. 2





# Planarization Capability

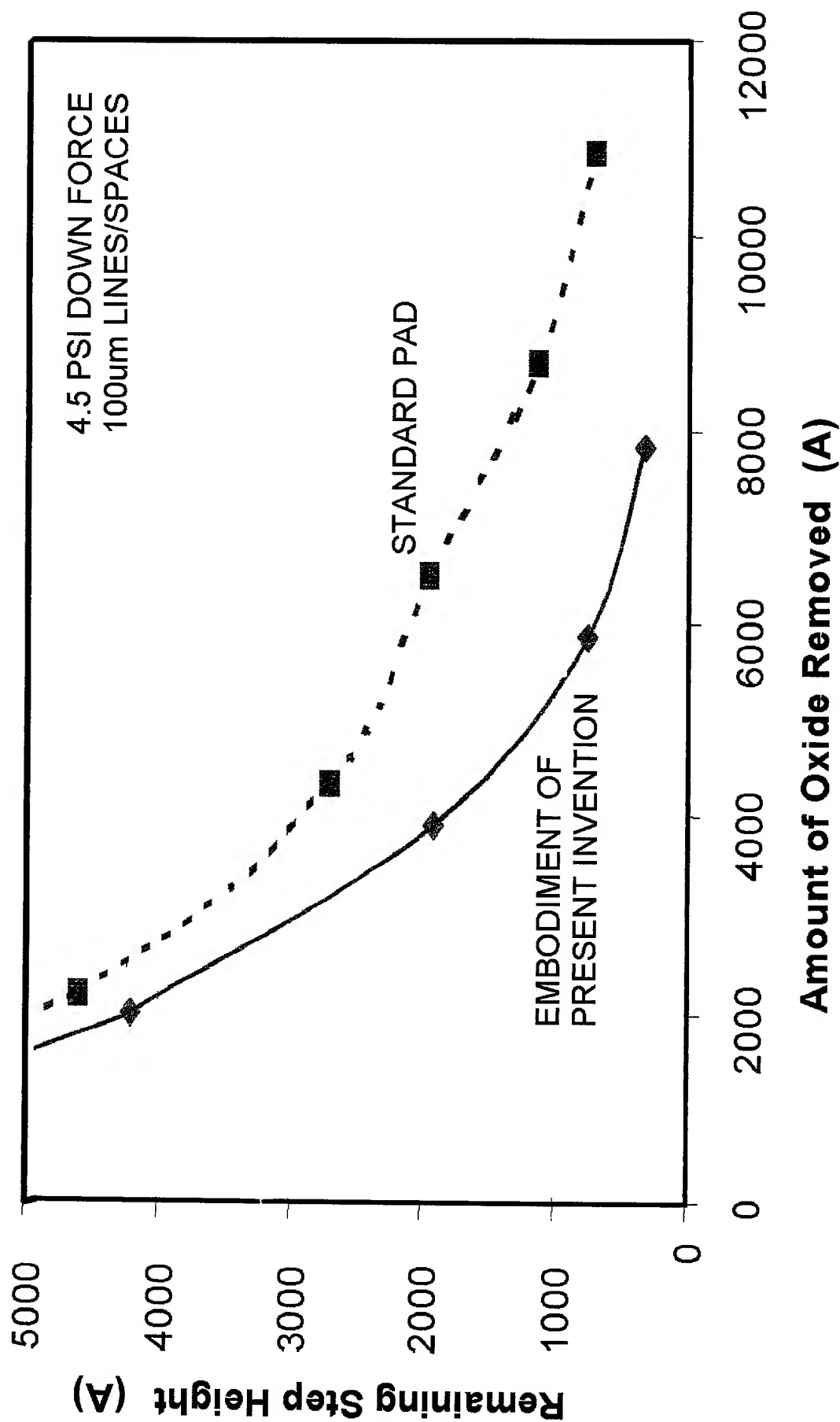


FIG. 4

# Cu Evaluation

## Cu Step 1 Planarization Efficiency

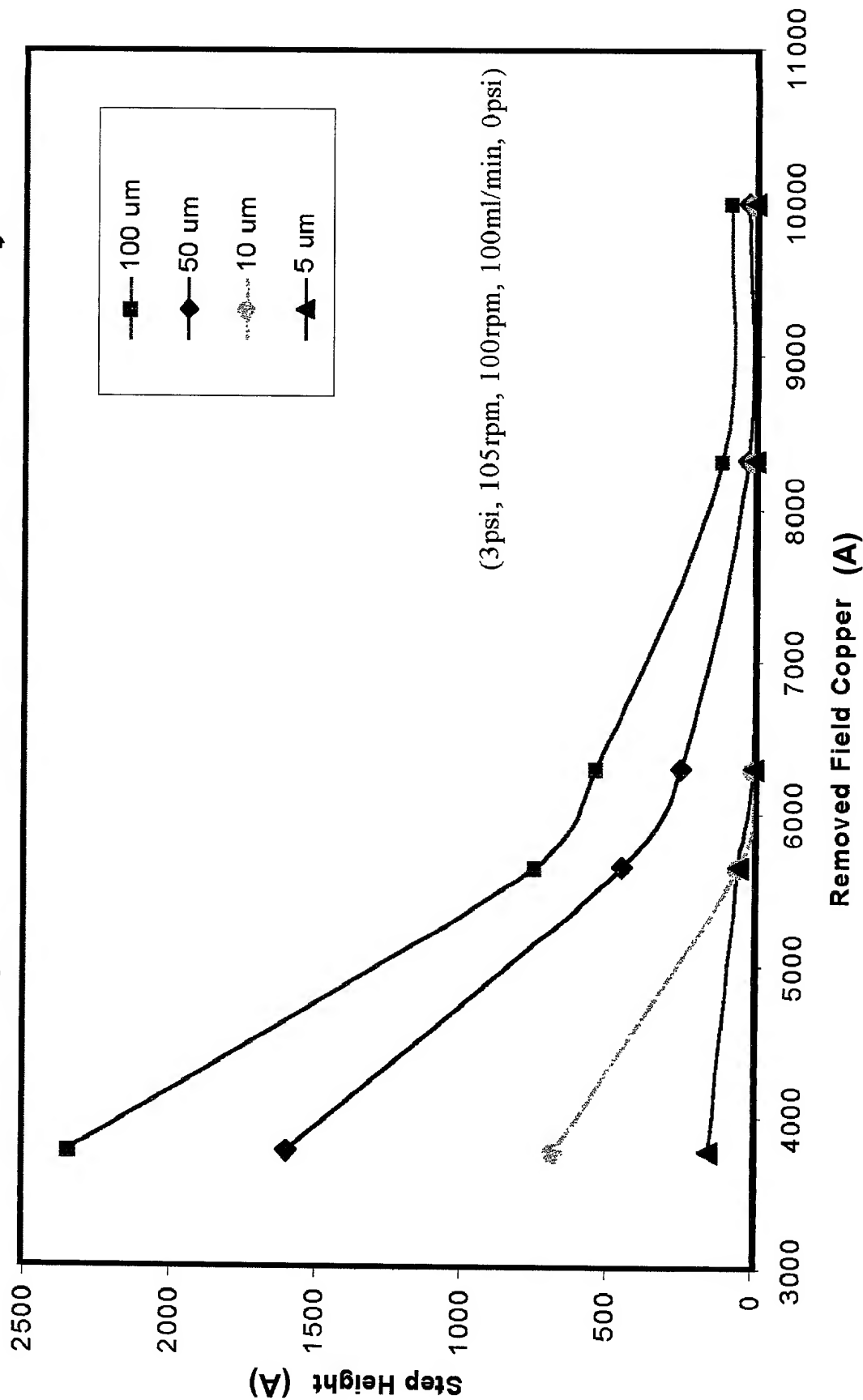


FIG. 5

Removal Rate (Å/min)

Polished wafer number

EKC 3550 W slurry

Legend:

- WNU (Open diamond)
- WRR (Filled diamond)
- TiRR (Filled triangle)
- DEFECTIVITY (Filled circle)

Polished wafer number	WNU (Å/min)	WRR (Å/min)	TiRR (Å/min)	DEFECTIVITY (%)
1	1850	4200		
2	1850	4200		
3	1850	4200		
4	1850	4200		
5	1850	4200		
6	1850	4200		
7	1850	4200		
8	1850	4200		
9	1850	4200		
10	1850	4200		
11	1850	4200		
12	1850	4200		
13	1850	4200		
14	1850	4200		
15	1850	4200		
16	1850	4200		
17	1850	4200		
18	1850	4200		
19	1850	4200		
20	1850	4200		
21	1850	4200		
22	1850	4200		
23	1850	4200		
24	1850	4200		
25	1850	4200		
26	1850	4200		
27	1850	4200		
28	1850	4200		
29	1850	4200		
30	1850	4200		
31	1850	4200		
32	1850	4200		
33	1850	4200		
34	1850	4200		
35	1850	4200		
36	1850	4200		
37	1850	4200		
38	1850	4200		
39	1850	4200		
40	1850	4200		

FIG. 6